

GOSTONE ROHS



GMS048NE4F1

N-Channel 45V,4.8mΩ max,SGT Power MOSFET

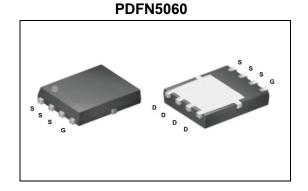
P	Product Summary							
	V _{DS} (V)	$R_{DS(on),max}$ (m Ω)	I _D (A)					
	45	4.8 @ V _{GS} = 10V	92 (1)					

Features

- Low R_{DS(on)} trench technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

Application

- DC/DC conversion
- Power switch
- Motor drives
- Li- Battery Protection



GMXXXX GS

FAYWWLT

PDFN5060

NOTE: LOGO - GS

GMXXXXX- Part number code

F - Fab location code

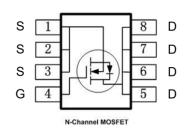
A - Assembly location code

Y - Year code

WW - Week code

L&T - Assembly lot code

Equivalent circuit



Absolute maximum rating@25℃

Parameter		Symbol	Limit	Unit
Drain-source voltage			45	.,
Gate-source voltage		V _{GS}	±20	V
	T _C =25°C ⁽¹⁾		92	А
Continuous drain current	T _C =100°C ⁽¹⁾	I _D	53	
Pulsed drain current ⁽²⁾	<u> </u>	I _{D,pulse}	326	
Avalanche energy, single pulse ⁽³⁾		E _{AS}	116	mJ
Dower discipation	T _C =25°C	D	54	W
Power dissipation	T _A =100°C	P _D	22	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to 150	°C

Thermal Characteristic

Parameter	Symbol	Max.	Unit		
Thermal resistance, junction-to-case	Steady state	Rejc	2.3	90/14/	
Thermal resistance, junction-to-ambient (4)	Steady state	Reja	50	°C/W	



Electrical Characteristics (TJ=25℃ unless otherwise noted)

Parameter	Symbol	Test conditions	Min.	Тур.	Max.	Unit	
Static parameter							
Drain to source breakdown voltage	$V_{(BR)DSS}$	V _{GS} = 0, I _D = 250 μA	45			V	
Gate-source threshold voltage	ve-source threshold voltage $V_{GS(th)}$ $V_{DS} = V_{GS}$, $I_D = 250 \mu A$		2.0	3.0	4.0	V	
Gate-body leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A		4.3	4.8	mΩ	
Forward transconductance (5)	g_{fs}	V _{DS} = 5 V, I _D = 30 A		15		S	
Gate resistance	Rg	f = 1 MHz		4.2		Ω	
Dynamic ⁽⁵⁾							
Total gate charge V _{GS} = 10V	Q_g			14		nC	
Total gate charge V _{GS} = 4.5V	Q_g	V_{DS} = 20 V, I_{D} = 20 A, V_{GS} = 10 V		8.7			
Gate-source charge	Q_gs	VDS - 20 V, ID - 20 A, VGS - 10 V		4.6			
Gate-drain charge	Q_{gd}			2.9			
Turn-on delay time	t _{d(on)}			5.7			
Rise time	t _r	V_{DS} = 20 V, I_{D} = 20 A, V_{GS} = 10 V,		11		no	
Turn-off delay time	t _{d(off)}	$R_{GEN} = 3 \Omega$		14		ns	
Fall time	t _f			8.0			
Input capacitance	C _{iss}			982			
Output capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		593		pF	
Reverse transfer capacitance	C_{rss}			25			
Reverse Diode Characteristics (5)							
Diode forward voltage	V _{SD}	V _{GS} = 0 V, I _F = 2 A		0.7	1.2	V	
Reverse recovery time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		30		ns	
Reverse recovery charge	Qrr	11 20 A, allat - 100 A/µ3		13		nC	

Notes

- (1) Limited by maximum junction temperature.
- (2) Pulse width limited by maximum junction temperature.
- (3) $V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, L = 1.0 \text{ mH}.$
- (4) Device mounted on FR-4 substrate PC board with 2oz copper in 1inch square cooling area.
- (5) Guaranteed by design, not subject to production testing.



Typical Performance Characteristics

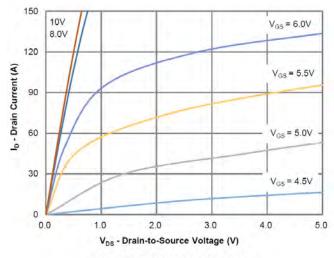


Figure 1: Output Characteristics

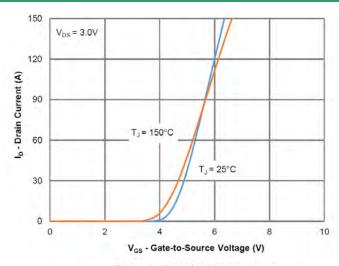


Figure 2: Transfer Characteristics

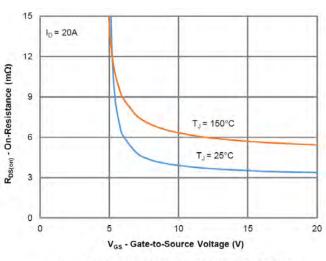


Figure 3: On-Resistance vs. Gate-Source Voltage

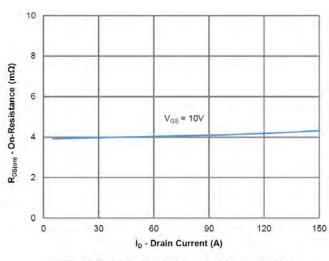


Figure 4: On-Resistance vs. Gate-Source Voltage

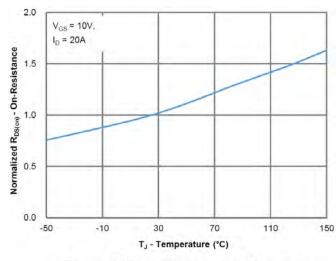


Figure 5: On-Resistance vs. Junction Temperature

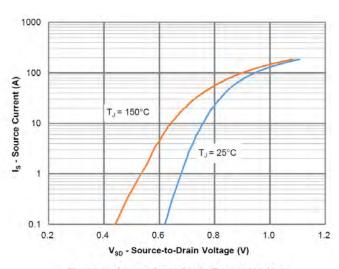


Figure 6: Source-Drain Diode Forward Voltage



Typical Performance Characteristics

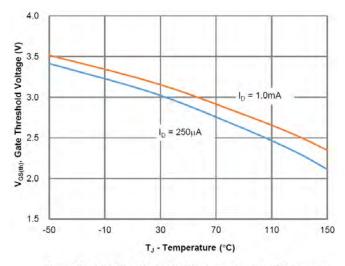


Figure 7: Gate Threshold Variation vs. Junction Temperature

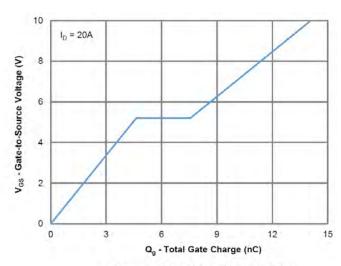


Figure 8: Gate Charge Characteristics

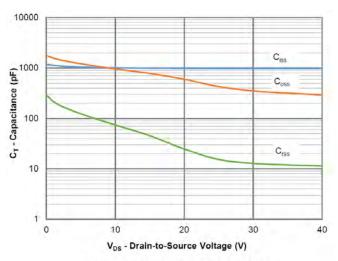


Figure 9: Capacitance Characteristics

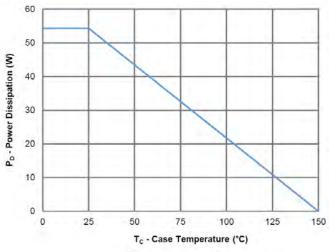


Figure 10: Power Derating

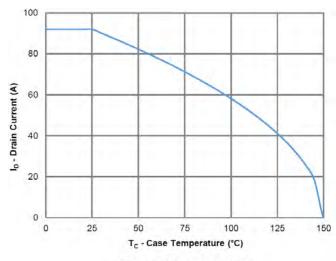


Figure 11: Current Derating

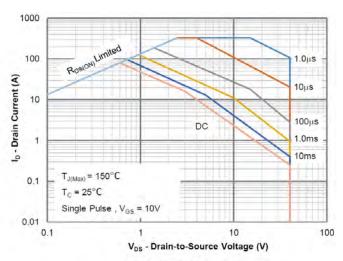


Figure 12: Safe Operating Area



Typical Performance Characteristics

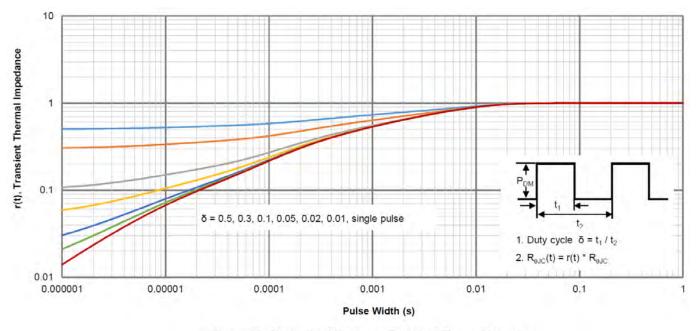
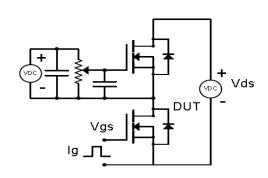


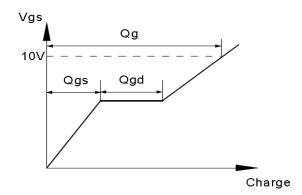
Figure 13: Normalized Maximum Transient Thermal Impedance



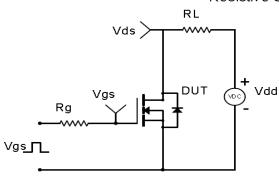
Test Circuit & Waveform

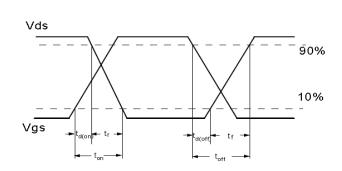
Gate Charge Test Circuit & Waveform



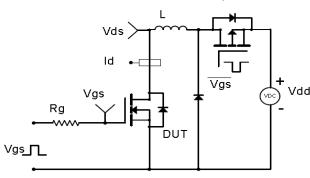


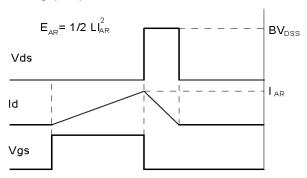
Resistive Switching Test Circuit & Waveforms



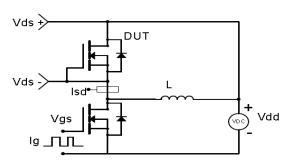


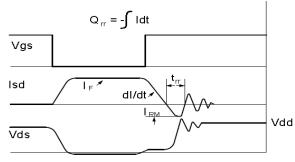
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





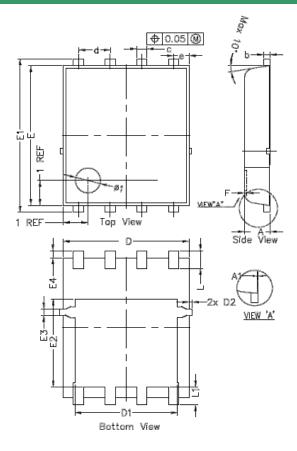
Diode Recovery Test Circuit & Waveforms







Outline Drawing PDFN5060



Direc	Millimeters				
Dim	Min	Nom	Max		
А	0.900	1.000	1.100		
A1	0.000		0.050		
b	0.246	0.254	0.312		
С	0.310	0.410	0.510		
d	1.27BSC				
D	4.950	5.050	5.150		
D1	4.000	4.100	4.200		
D2			0.125		
е	0.62BSC				
E	5.500	5.600	5.700		
E1	6.050	6.150	6.250		
E2	3.425	3.525	3.625		
E3	0.150	0.250	0.350		
E4	0.175	0.275	0.375		
F			0.100		
L	0.500	0.600	0.700		
L1	0.600	0.700	0.800		



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